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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-256-128-10ync

Table 1. ispMACH 4A Device Features

3.3 V Devices								
Feature	M4A3-32	M4A3-64	M4A3-96	M4A3-128	M4A3-192	M4A3-256	M4A3-384	M4A3-512
Macrocells	32	64	96	128	192	256	384	512
User I/O options	32	32/64	48	64	96	128/160/192	160/192	160/192/256
t_{PD} (ns)	5.0	5.5	5.5	5.5	6.0	5.5	6.5	7.5
f_{CNT} (MHz)	182	167	167	167	160	167	154	125
t_{COS} (ns)	4.0	4.0	4.0	4.0	4.5	4.0	4.5	5.5
t_{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5	3.5	5.0
Static Power (mA)	20	25/52	40	55	85	110/150	149/155	179
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

5 V Devices						
Feature	M4A5-32	M4A5-64	M4A5-96	M4A5-128	M4A5-192	M4A5-256
Macrocells	32	64	96	128	192	256
User I/O options	32	32	48	64	96	128
t_{PD} (ns)	5.0	5.5	5.5	5.5	6.0	6.5
f_{CNT} (MHz)	182	167	167	167	160	154
t_{COS} (ns)	4.0	4.0	4.0	4.0	4.5	5.0
t_{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5
Static Power (mA)	20	25	40	55	74	110
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes

Table 4. Architectural Summary of ispMACH 4A devices

	ispMACH 4A Devices	
	M4A3-64/32, M4A5-64/32 M4A3-96/48, M4A5-96/48 M4A3-128/64, M4A5-128/64 M4A3-192/96, M4A5-192/96 M4A3-256/128, M4A5-256/128 M4A3-384 M4A3-512	M4A3-32/32 M4A5-32/32 M4A3-64/64 M4A3-256/160 M4A3-256/192
Macrocell-I/O Cell Ratio	2:1	1:1
Input Switch Matrix	Yes	Yes ¹
Input Registers	Yes	No
Central Switch Matrix	Yes	Yes
Output Switch Matrix	Yes	Yes

The Macrocell-I/O cell ratio is defined as the number of macrocells versus the number of I/O cells internally in a PAL block (Table 4).

The central switch matrix takes all dedicated inputs and signals from the input switch matrices and routes them as needed to the PAL blocks. Feedback signals that return to the same PAL block still must go through the central switch matrix. This mechanism ensures that PAL blocks in ispMACH 4A devices communicate with each other with consistent, predictable delays.

The central switch matrix makes a ispMACH 4A device more advanced than simply several PAL devices on a single chip. It allows the designer to think of the device not as a collection of blocks, but as a single programmable device; the software partitions the design into PAL blocks through the central switch matrix so that the designer does not have to be concerned with the internal architecture of the device.

Each PAL block consists of:

- ◆ Product-term array
- ◆ Logic allocator
- ◆ Macrocells
- ◆ Output switch matrix
- ◆ I/O cells
- ◆ Input switch matrix
- ◆ Clock generator

Notes:

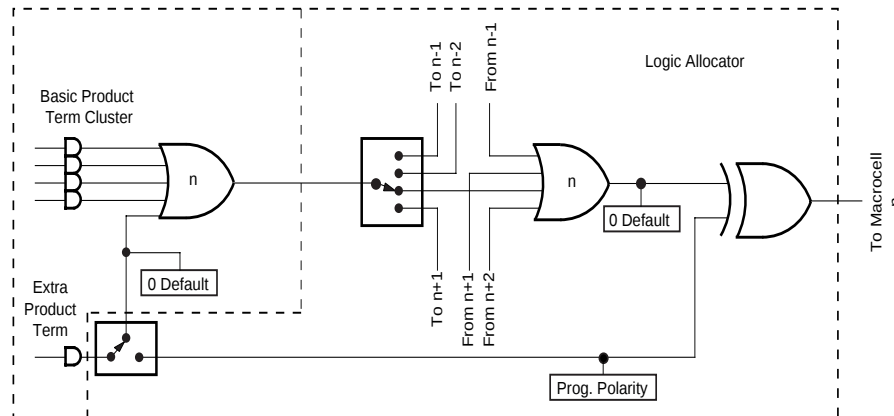
1. M4A3-64/64 internal switch matrix functionality embedded in central switch matrix.

Table 6. Logic Allocator for All ispMACH 4A Devices (except M4A(3,5)-32/32)

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₇ , C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇ , C ₈	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇ , C ₈ , C ₉	M ₁₅	C ₁₄ , C ₁₅

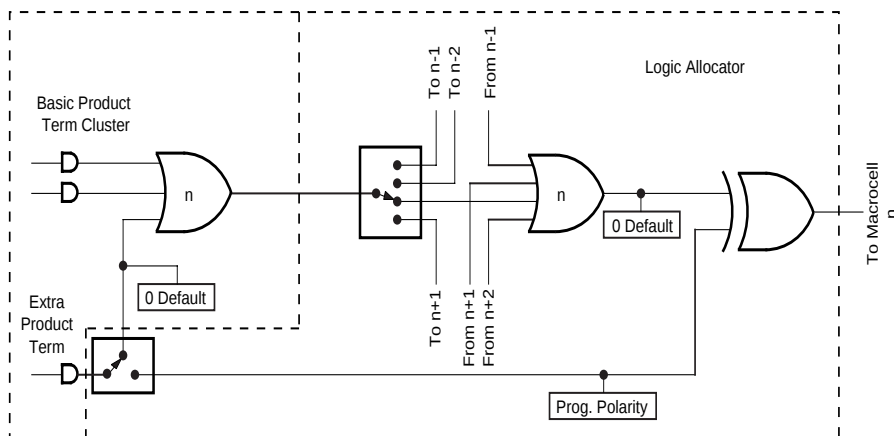
Table 7. Logic Allocator for M4A(3,5)-32/32

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇	M ₁₅	C ₁₄ , C ₁₅



a. Synchronous Mode

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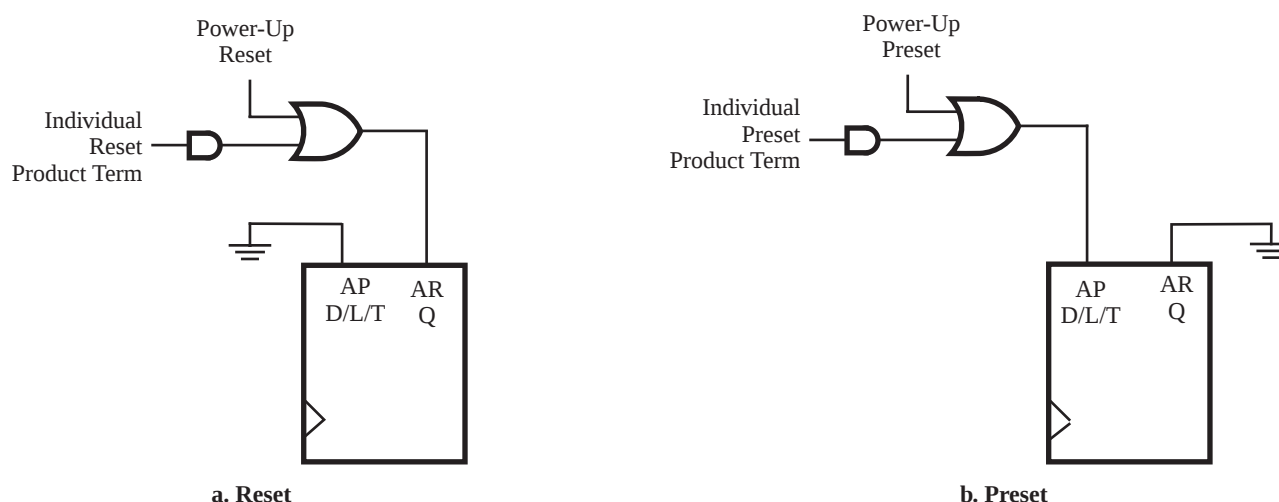


b. Asynchronous Mode

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Figure 2. Logic Allocator: Configuration of Cluster “n” Set by Mode of Macrocell “n”

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.



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Figure 8. Asynchronous Mode Initialization Configurations

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

Table 9. Asynchronous Reset/Preset Operation

AR	AP	CLK/LE ¹	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

Note:

- Transparent latch is unaffected by AR, AP

Output Switch Matrix

The output switch matrix allows macrocells to be connected to any of several I/O cells within a PAL block. This provides high flexibility in determining pinout and allows design changes to occur without effecting pinout.

In ispMACH 4A devices with 2:1 Macrocell-I/O cell ratio, each PAL block has twice as many macrocells as I/O cells. The ispMACH 4A output switch matrix allows for half of the macrocells to drive I/O cells within a PAL block, in combinations according to Figure 9. Each I/O cell can choose from eight macrocells; each macrocell has a choice of four I/O cells. The ispMACH 4A devices with 1:1 Macrocell-I/O cell ratio allow each macrocell to drive one of eight I/O cells (Figure 9).

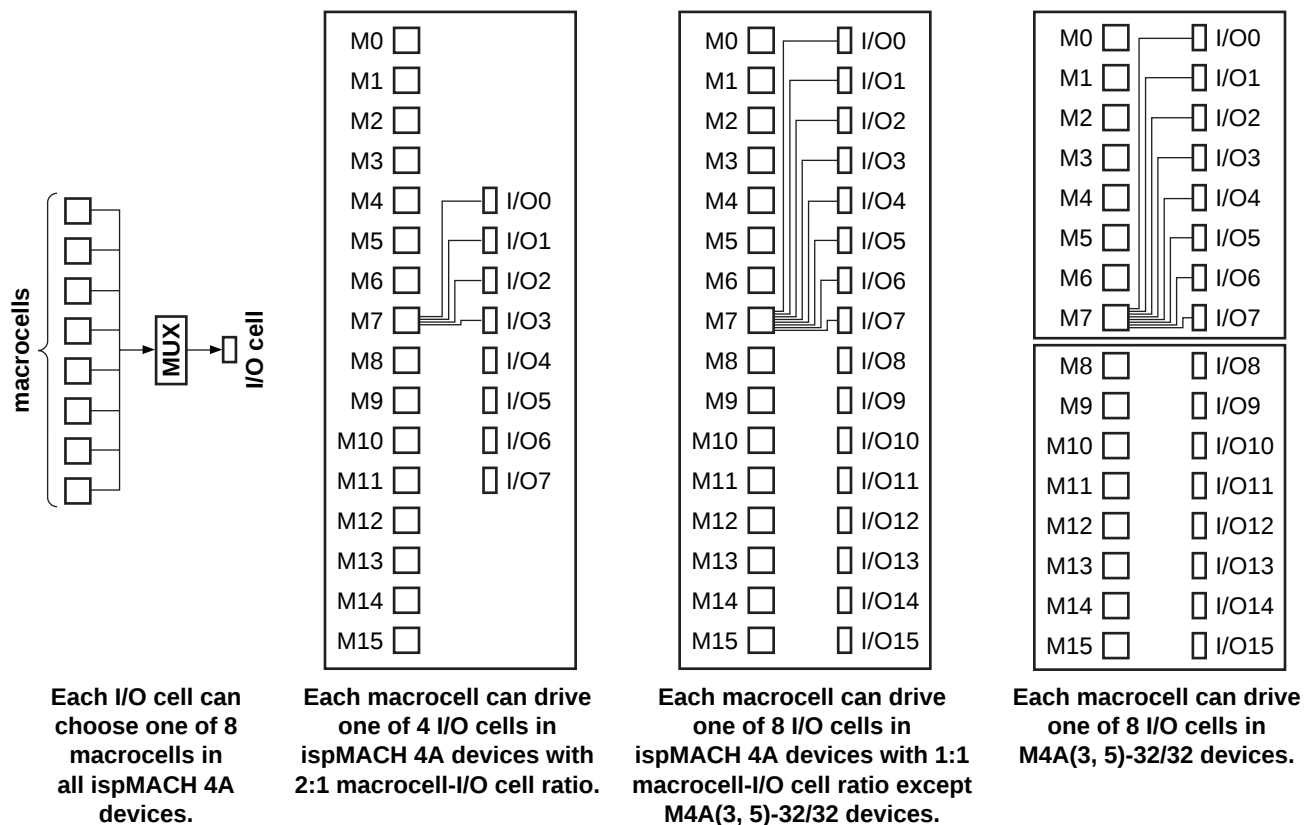


Figure 9. ispMACH 4A Output Switch Matrix

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routeable to I/O Cells
M0, M1	I/O0, I/O5, I/O6, I/O7
M2, M3	I/O0, I/O1, I/O6, I/O7
M4, M5	I/O0, I/O1, I/O2, I/O7
M6, M7	I/O0, I/O1, I/O2, I/O3
M8, M9	I/O1, I/O2, I/O3, I/O4
M10, M11	I/O2, I/O3, I/O4, I/O5

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/O3, I/O4, I/O5, I/O6
M14, M15	I/O4, I/O5, I/O6, I/O7

I/O Cell	Available Macrocells
I/O0	M0, M1, M2, M3, M4, M5, M6, M7
I/O1	M2, M3, M4, M5, M6, M7, M8, M9
I/O2	M4, M5, M6, M7, M8, M9, M10, M11
I/O3	M6, M7, M8, M9, M10, M11, M12, M13
I/O4	M8, M9, M10, M11, M12, M13, M14, M15
I/O5	M0, M1, M10, M11, M12, M13, M14, M15
I/O6	M0, M1, M2, M3, M12, M13, M14, M15
I/O7	M0, M1, M2, M3, M4, M5, M14, M15

Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M1	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M2	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M3	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M4	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M5	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M6	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M7	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M8	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M9	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M10	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M11	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M12	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M13	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M14	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M15	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15

I/O Cell	Available Macrocells							
I/O0	M0	M1	M2	M3	M4	M5	M6	M7
I/O1	M0	M1	M2	M3	M4	M5	M6	M7
I/O2	M0	M1	M2	M3	M4	M5	M6	M7
I/O3	M0	M1	M2	M3	M4	M5	M6	M7
I/O4	M0	M1	M2	M3	M4	M5	M6	M7
I/O5	M0	M1	M2	M3	M4	M5	M6	M7
I/O6	M0	M1	M2	M3	M4	M5	M6	M7
I/O7	M0	M1	M2	M3	M4	M5	M6	M7

IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary ScanTest Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V V_{CC} ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level “1.” For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are

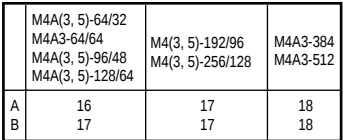


Figure 16. PAL Block for ispMACH 4A with 2:1 Macrocell - I/O Cell Ratio

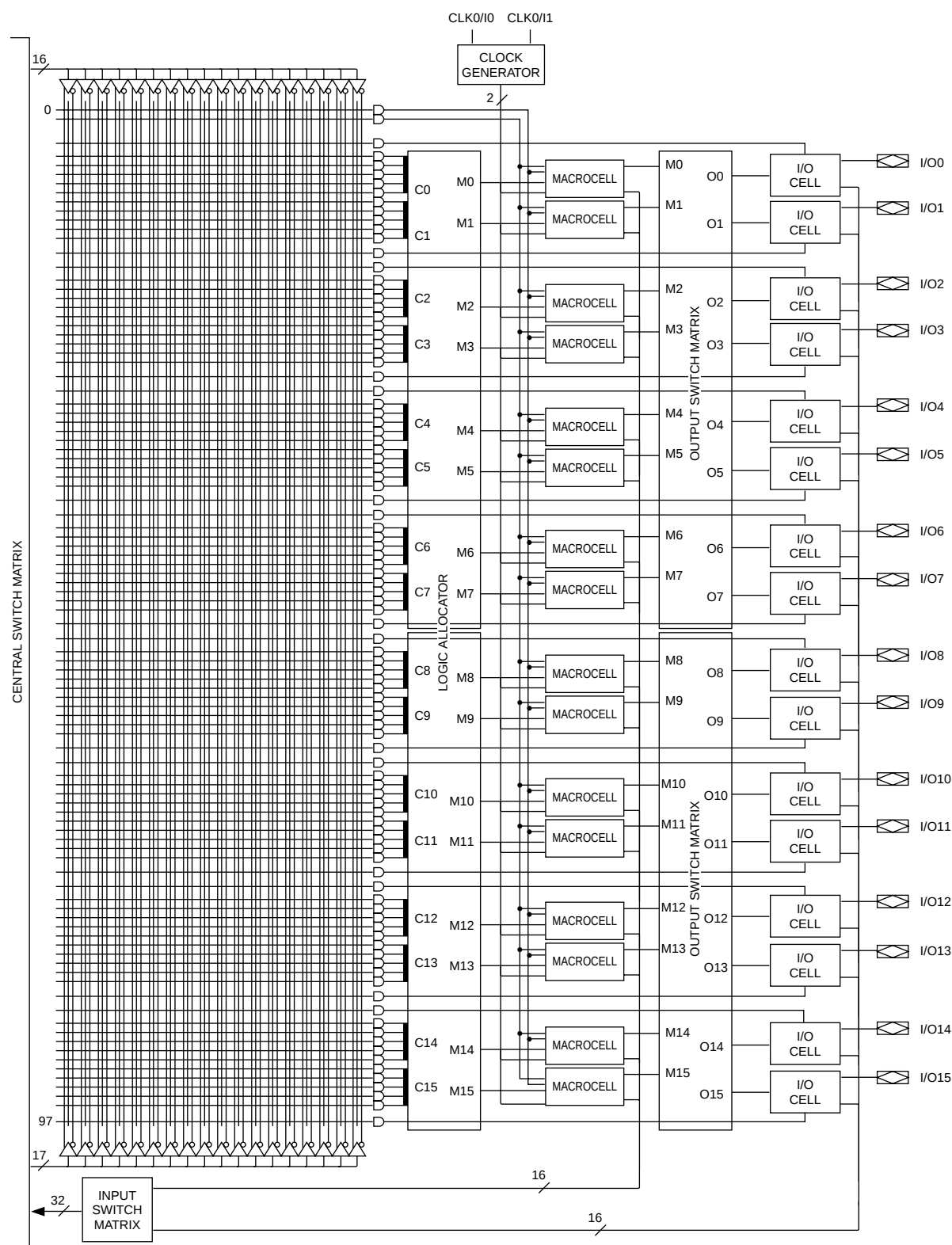
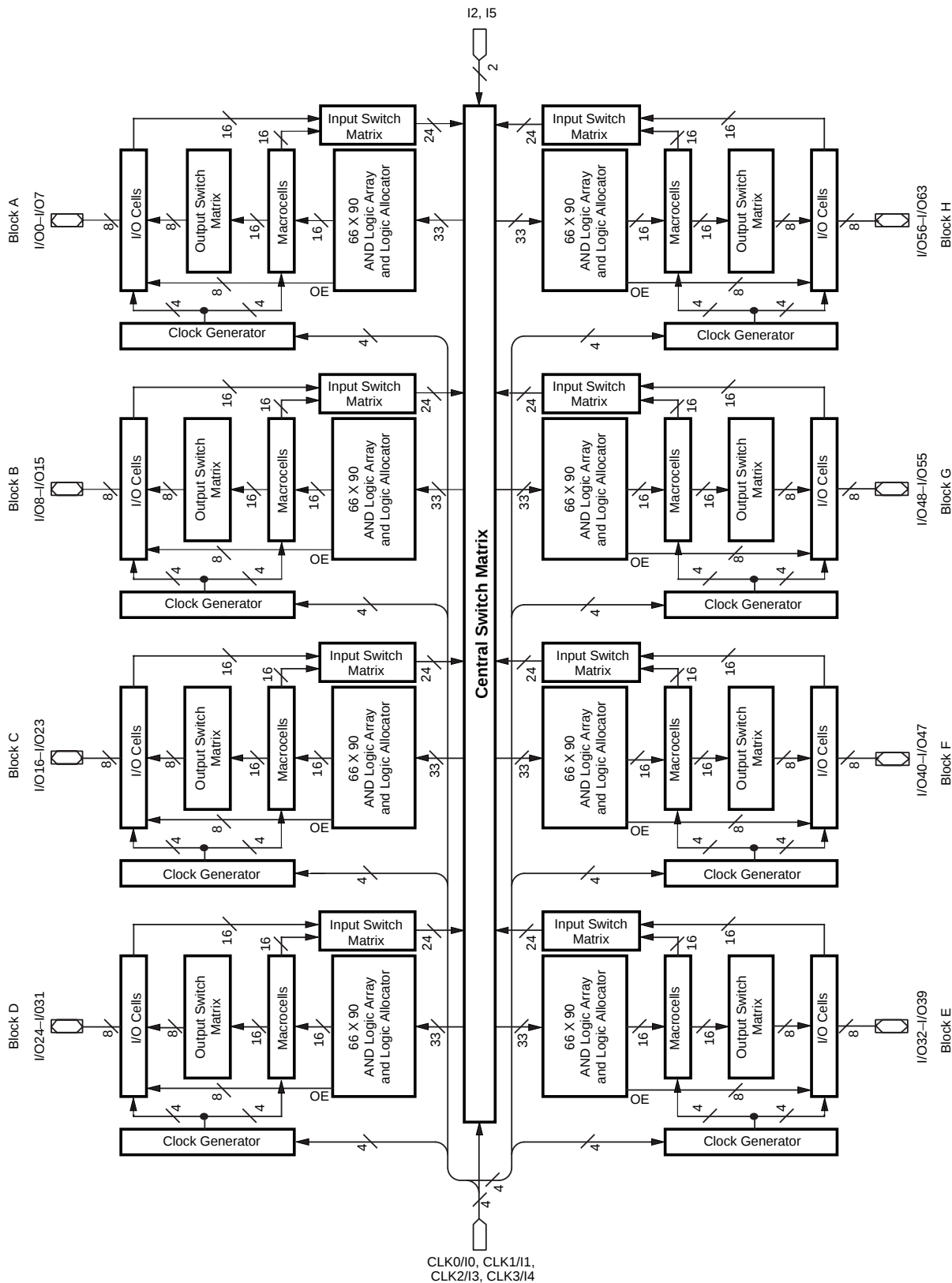


Figure 18. PAL Block for M4A (3,5)-32/32

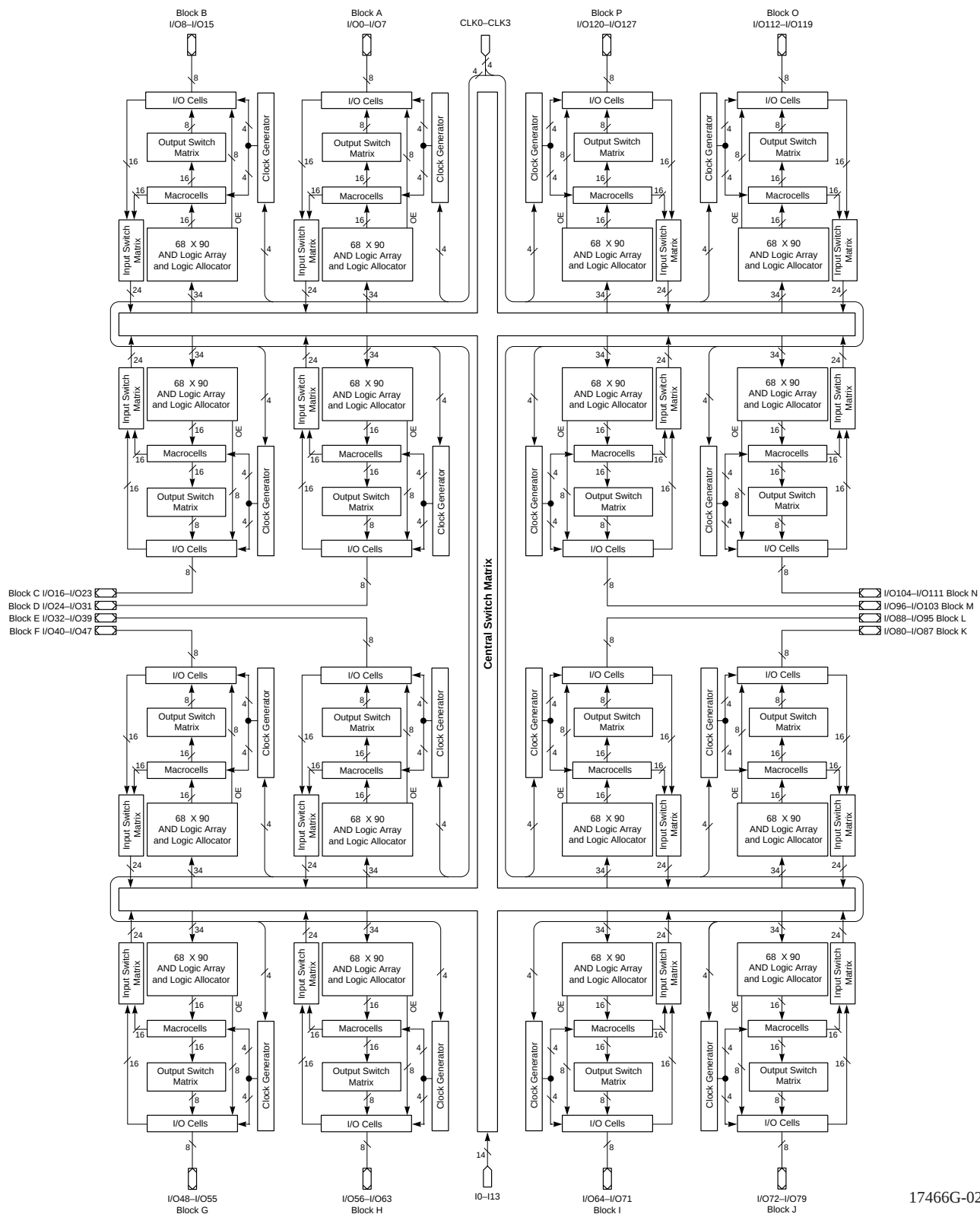
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BLOCK DIAGRAM – M4A(3,5)-128/64



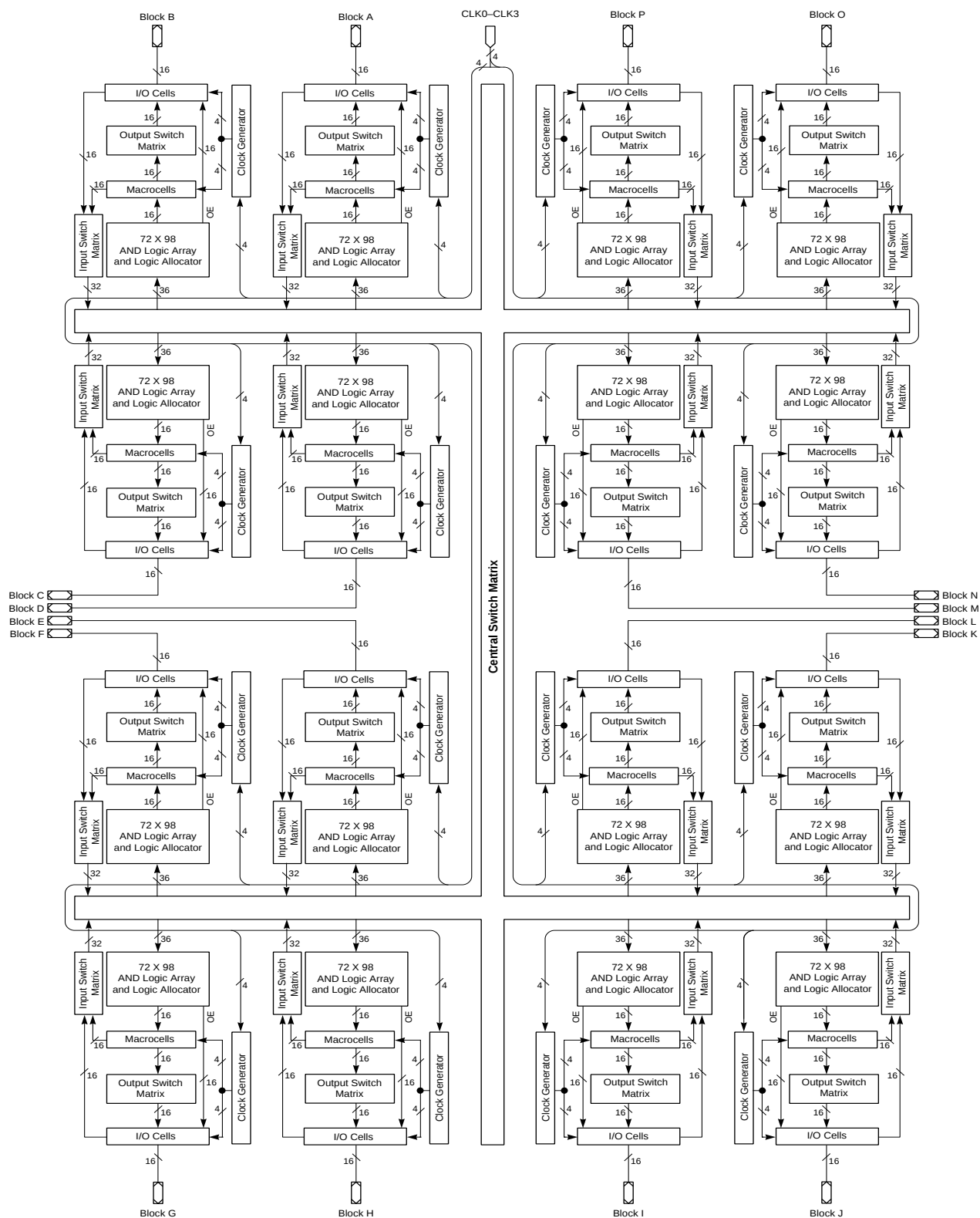
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BLOCK DIAGRAM – M4A(3,5)-256/128



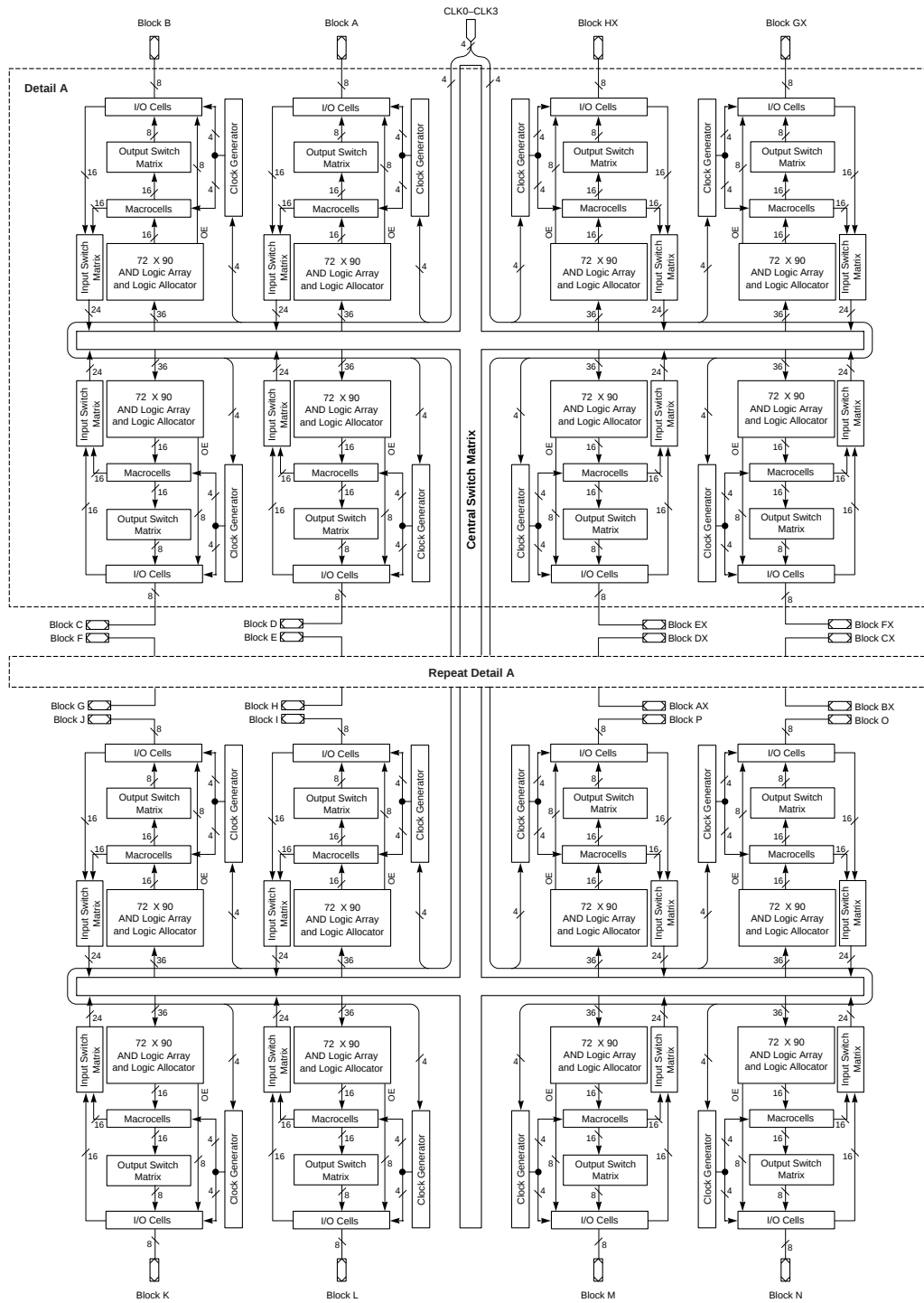
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BLOCK DIAGRAM – M4A3-256/160, M4A3-256/192



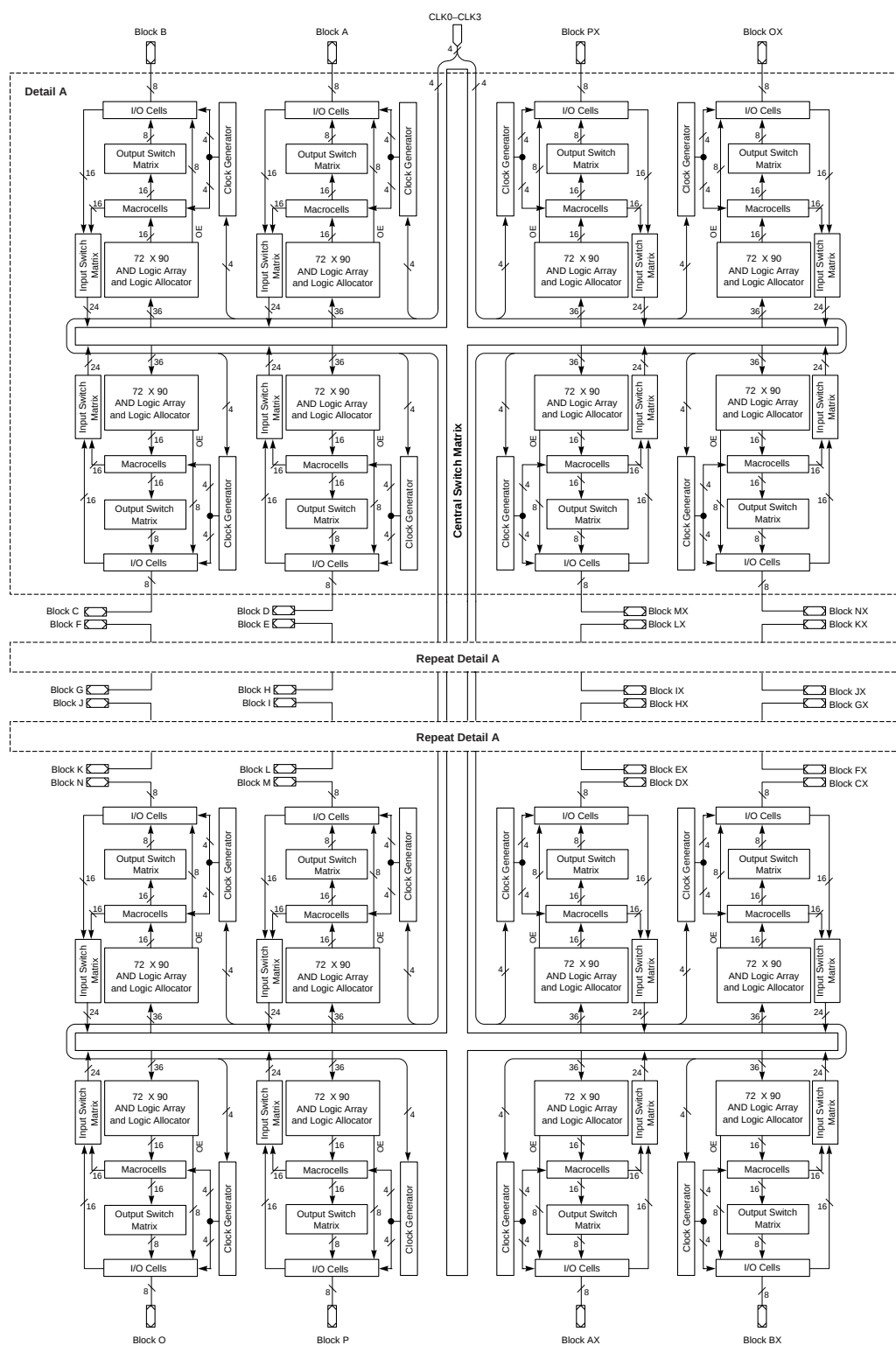
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BLOCK DIAGRAM – M4A3-384/160, M4A3-384/192



17466G-067

BLOCK DIAGRAM - M4A3-512/160, M4A3-512/192, M4A3-512/256



17466G-068

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground. -0.5 V to +4.5 V
 DC Input Voltage. -0.5 V to 6.0 V
 Static Discharge Voltage. 2000 V
 Latchup Current ($T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^{\circ}\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^{\circ}\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -100\ \mu\text{A}$	$V_{CC} - 0.2$			V
			$I_{OH} = -3.2\ \text{mA}$	2.4			V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 1)	$I_{OL} = 100\ \mu\text{A}$			0.2	V
			$I_{OL} = 24\ \text{mA}$			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		-0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				5	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				-5	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				5	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				-5	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5\ \text{V}$, $V_{CC} = \text{Max}$ (Note 3)		-15		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Notes:

1. See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.
2. This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Input Register Delays with ZHT Option:																		
t _{SIRZ}	Input register setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HIRZ}	Input register hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
Input Latch Delays with ZHT Option:																		
t _{SILZ}	Input latch setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HILZ}	Input latch hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{PDIL} Z _i	Transparent input latch to internal feedback - ZHT		6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0	ns
Output Delays:																		
t _{BUF}	Output buffer delay		1.5		1.5		1.8		2.0		2.5		3.0		3.0		3.0	ns
t _{SLW}	Slow slew rate delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
t _{ER}	Output disable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
Power Delay:																		
t _{PL}	Power-down mode delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
Reset and Preset Delays:																		
t _{SRI}	Asynchronous reset or preset to internal register output		7.5		7.7		8.0		8.0		9.5		11.0		13.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		9.0		9.2		10.0		10.0		12.0		14.0		16.0		19.0	ns
t _{SRR}	Asynchronous reset and preset register recovery time	7.0		7.0		7.5		7.5		8.0		8.0		10.0		15.0		ns
t _{SRW}	Asynchronous reset or preset width	7.0		7.0		8.0		8.0		10.0		10.0		12.0		15.0		ns
Clock/LE Width:																		
t _{WLS}	Global clock width low	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WHS}	Global clock width high	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{WHA}	Product term clock width high	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{GWS}	Global gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns
t _{GWA}	Product term gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		9.0		ns
t _{WIRL}	Input register clock width low	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIRH}	Input register clock width high	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIL}	Input latch gate width	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power.

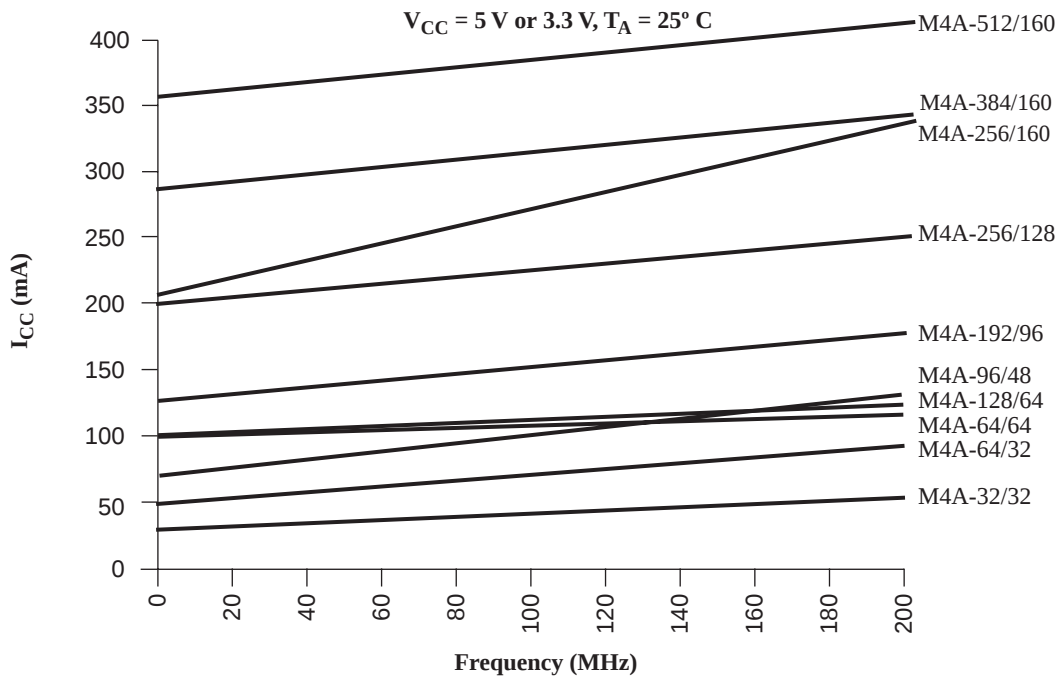


Figure 19. ispMACH 4A I_{CC} Curves at High Speed Mode

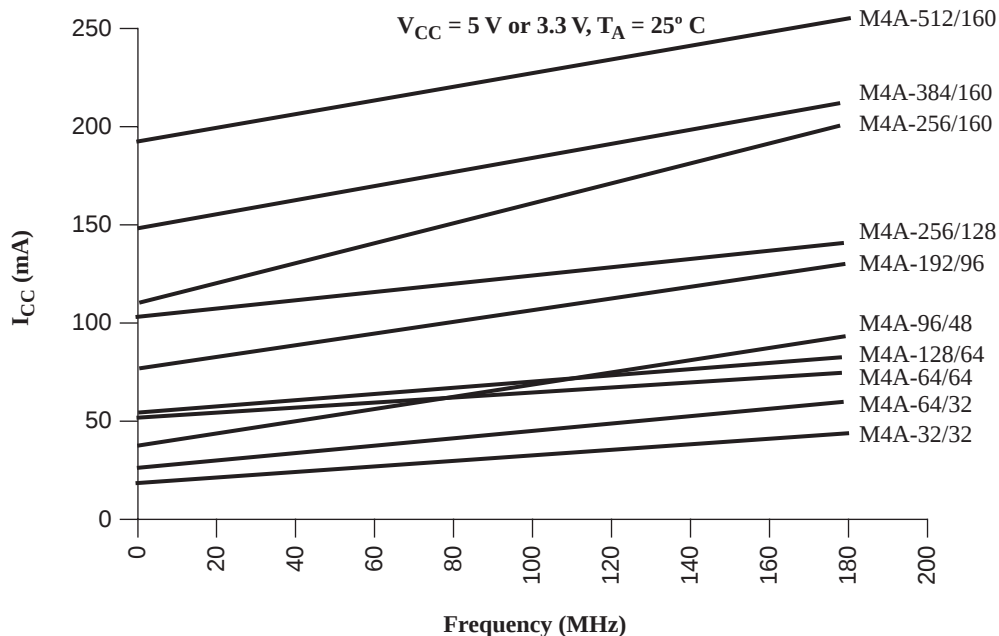
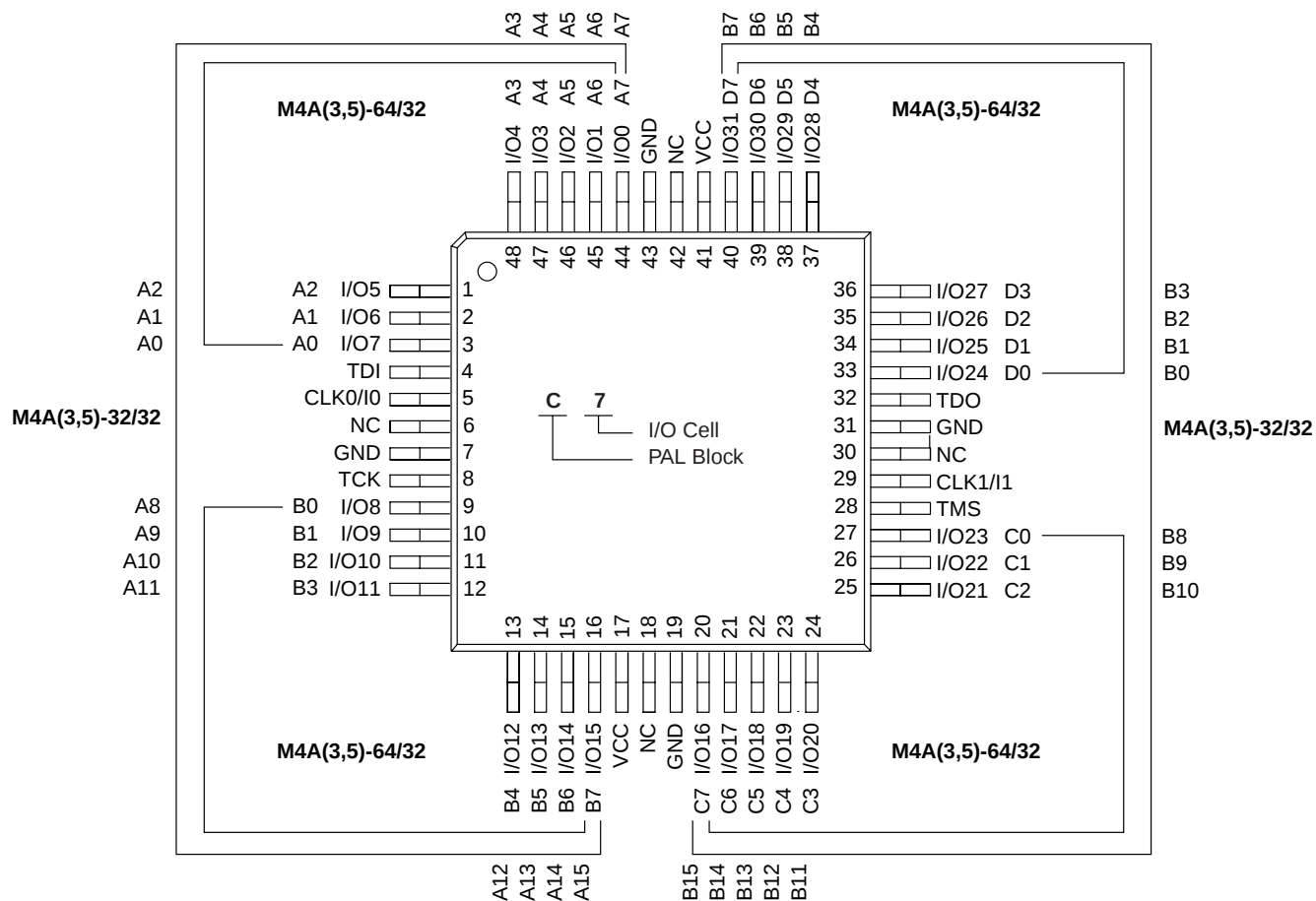


Figure 20. ispMACH 4A I_{CC} Curves at Low Power Mode

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



17466G-028

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-384/192)

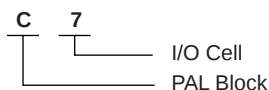
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O175 FX7	I/O181 GX5	I/O180 GX4	I/O177 GX1	I/O166 EX6	I/O164 EX4	I/O191 HX7	I/O186 HX2	I/O1 A1	I/O3 A3	CLK0	I/O25 D1	I/O29 D5	I/O31 D7	I/O10 B2	I/O12 B4	A
B	I/O173 FX5	I/O174 FX6	I/O182 GX6	I/O179 GX3	I/O167 EX7	I/O165 EX5	I/O160 EX0	I/O187 HX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O26 D2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O171 FX3	I/O172 FX4	N/C	I/O183 GX7	I/O178 GX2	I/O162 EX2	I/O163 EX3	I/O189 HX5	I/O184 HX0	I/O6 A6	I/O28 D4	I/O30 D6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	C
D	I/O150 CX6	I/O151 CX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	D
E	I/O148 CX4	N/C	I/O170 FX2	VCC	I/O168 FX0	169 FX1	I/O190 HX6	CLK3	I/O188 HX4	I/O2 A2	I/O24 D0	N/C	GND	I/O20 C4	I/O19 C3	I/O47 F7	E
F	I/O144 CX0	I/O149 CX5	I/O147 CX3	GND	I/O146 CX2	I/O145 CX1	I/O176 GX0	I/O161 EX1	I/O185 HX1	I/O4 A4	I/O27 D3	I/O18 C2	VCC	I/O16 C0	I/O46 F6	I/O45 F5	F
G	I/O155 DX3	I/O158 DX6	I/O157 DX5	VCC	I/O156 DX4	I/O159 DX7	VCC	GND	GND	VCC	I/O17 C1	I/O44 F4	GND	I/O42 F2	I/O41 F1	I/O39 E7	G
H	I/O152 DX0	I/O154 DX2	I/O153 DX1	GND	I/O128 AX0	I/O129 AX1	GND	VCC	VCC	GND	I/O43 F3	I/O40 F0	VCC	I/O36 E4	I/O35 E3	I/O34 E2	H
J	I/O130 AX2	I/O131 AX3	I/O132 AX4	GND	I/O134 AX6	I/O133 AX5	GND	VCC	VCC	GND	I/O38 E6	I/O37 E5	GND	I/O57 H1	I/O56 H0	I/O58 H2	J
K	I/O135 AX7	I/O136 BX0	I/O137 BX1	VCC	I/O139 BX3	I/O138 BX2	VCC	GND	GND	VCC	I/O33 E1	I/O32 E0	VCC	I/O63 H7	I/O62 H6	I/O48 G0	K
L	I/O140 BX4	I/O141 BX5	I/O143 BX7	GND	I/O114 O2	I/O142 BX6	I/O98 M2	I/O91 L3	I/O67 I3	I/O69 I5	I/O60 H4	I/O59 H3	GND	I/O51 G3	I/O52 G4	I/O49 G1	L
M	I/O112 O0	I/O113 O1	I/O115 O3	GND	I/O123 P3	I/O121 P1	I/O100 M4	I/O90 L2	I/O66 I2	I/O80 K0	I/O83 K3	I/O61 H5	VCC	I/O76 J4	I/O55 G7	I/O50 G2	M
N	I/O116 O4	I/O117 O5	I/O119 O7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O72 J0	I/O53 G5	N
P	I/O118 O6	I/O109 N5	I/O110 N6	I/O111 N7	I/O124 P4	I/O122 P2	I/O101 M5	I/O89 L1	I/O93 L5	I/O94 L6	I/O71 I7	I/O84 K4	I/O87 K7	TMS	I/O73 J1	I/O54 G6	P
R	I/O108 N4	I/O107 N3	I/O104 N0	I/O127 P7	I/O120 P0	I/O102 M6	I/O99 M3	I/O96 M0	I/O92 L4	I/O64 I0	I/O68 I4	I/O81 K1	I/O85 K5	I/O79 J7	I/O75 J3	I/O74 J2	R
T	I/O106 N2	I/O105 N1	I/O126 P6	I/O125 P5	I/O103 M7	CLK2	I/O97 M1	I/O88 L0	CLK1	I/O95 L7	I/O65 I1	I/O70 I6	I/O82 K2	I/O86 K6	I/O78 J6	I/O77 J5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



m4a3.384.192_256bga

ispMACH 4A PRODUCT ORDERING INFORMATION

ispMACH 4A Devices Commercial and Industrial - 3.3V and 5V

Lattice programmable logic products are available with several ordering options. The order number (Valid Combination) is formed by a combination of:

M4A3- 256 / 128 -7 Y C		L48	
FAMILY TYPE		= 48-pin TQFP for M4A3-32/32 or M4A3-64/32 M4A5-32/32 or M4A5-64/32	
M4A3- = ispMACH 4A Family Low Voltage Advanced Feature (3.3-V V_{CC})		OPERATING CONDITIONS	
M4A5- = ispMACH 4A Family Advanced Feature (5-V V_{CC})		C = Commercial (0°C to +70°C)	
MACROCELL DENSITY		I = Industrial (-40°C to +85°C)	
32 = 32 Macrocells 192 = 192 Macrocells		PACKAGE TYPE	
64 = 64 Macrocells 256 = 256 Macrocells		SA = Ball Grid Array (BGA)	
96 = 96 Macrocells 384 = 384 Macrocells		J = Plastic Leaded Chip Carrier (PLCC)	
128 = 128 Macrocells 512 = 512 Macrocells		JN = Lead-free Plastic Leaded Chip Carrier (PLCC)	
I/Os		V = Thin Quad Flat Pack (TQFP)	
/32 = 32 I/Os in 44-pin PLCC, 44-pin TQFP or 48-pin TQFP		VN = Lead-free Thin Quad Flat Pack (TQFP)	
/48 = 48 I/Os in 100-pin TQFP		Y = Plastic Quad Flat Pack (PQFP)	
/64 = 64 I/Os in 100-pin TQFP, 100-pin PQFP, or 100-ball caBGA		YN = Lead-free Plastic Quad Flat Pack (PQFP)	
/96 = 96 I/Os in 144-pin TQFP or 144-ball fpBGA		FA = Fine-pitch Ball Grid Array (fpBGA)	
/128 = 128 I/Os in 208-pin PQFP, 256-ball BGA or 256-ball fpBGA		FAN = Lead-free Fine-pitch Ball Grid Array (fpBGA)	
/160 = 160 I/Os in 208-pin PQFP		CA = Chip-array Ball Grid Array (caBGA)	
/192 = 192 I/Os in 256-ball BGA or 256-ball fpBGA		SPEED	
/256 = 256 I/Os in 388-ball fpBGA		-5 = 5.0 ns t_{PD}	
		-55 = 5.5 ns t_{PD}	
		-6 = 6.0 ns t_{PD}	
		-65 = 6.5 ns t_{PD}	
		-7 = 7.5 ns t_{PD}	
		-10 = 10 ns t_{PD}	
		-12 = 12 ns t_{PD}	
		-14 = 14 ns t_{PD}	

*Package obsolete, contact factory.

Conventional Packaging

3.3V Commercial Combinations			3.3V Industrial Combinations		
M4A3-32/32	-5, -7, -10	JC, VC, VC48	M4A3-32/32	-7, -10, -12	JI, VI, VI48
M4A3-64/32	-55, -7, -10	JC, VC, VC48	M4A3-64/32		JI, VI, VI48
M4A3-64/64		VC	M4A3-64/64		VI
M4A3-96/48		VC	M4A3-96/48		VI
M4A3-128/64		YC, VC, CAC	M4A3-128/64		YI, VI, CAI
M4A3-192/96	-6, -7, -10	VC, FAC	M4A3-192/96		VI, FAI
M4A3-256/128	-55, -65 ¹ , -7, -10	YC, FAC, SAC	M4A3-256/128	-10, -12	YI, FAI, SAI
M4A3-256/160	-7, -10	YC	M4A3-256/160		YI
M4A3-256/192		FAC	M4A3-256/192	-10, -12, -14	FAI
M4A3-384/160	-65, -10, -12	YC	M4A3-384/160		YI
M4A3-384/192		SAC, FAC	M4A3-384/192		FAI
M4A3-512/160	-7, -10, -12	YC	M4A3-512/160		YI
M4A3-512/192		FAC	M4A3-512/192		FAI
M4A3-512/256		FAC	M4A3-512/256		FAI

1. Use 5.5ns for new designs.